

**CLAIM AMENDMENTS:**

Claims 1-4 (Canceled).

Claim 5 (Currently Amended): A semiconductor device, ~~as claimed in claim 1, in~~  
~~which comprising:~~

a lead frame having inner connecting portions and outer connecting  
portions;

a semiconductor chip having electrodes on a surface thereof;

metal wires for electrically connecting the electrodes on the semiconductor  
chip and the inner connecting portions of the lead frame;

a sealing resin for sealing the inner connecting portions of the lead frame,  
the semiconductor chip and the metal wires therein, and at the same time exposing the  
outer connecting portions of the lead frame at a bottom surface thereof; and

an inner connecting portion sealing resin for covering the inner connecting  
portion at the bottom side of the sealing resin; wherein

the inner connecting portion sealing resin exists beneath the connecting  
portion of the inner connecting portion with the metal wires;

a head end of the outer connecting portion is substantially in a same plane  
with a side surface of the sealing resin, the head end of the outer connecting portion  
having no chipped portion.

Claims 6-13 (Canceled):

Claim 14 (Newly Presented): A semiconductor device comprising:

a lead frame having inner connecting portions and outer connecting portions;

a semiconductor chip having electrodes on a surface thereof;

metal wires for electrically connecting the electrodes on the semiconductor chip and the inner connecting portions of the lead frame;

a sealing resin for sealing the inner connecting portions of the lead frame, the semiconductor chip and the metal wires therein, and at the same time exposing the outer connecting portions of the lead frame at a bottom surface thereof; and

an inner connecting portion sealing resin for covering the inner connecting portion at the bottom side of the sealing resin; wherein

the inner connecting portion sealing resin exists beneath the connecting portion of the inner connecting portion with the metal wires;

each of the metal wires is bonded to an upper surface of the inner connecting portion;

a lower surface of the inner connecting portion is offset inwardly of the sealing resin with respect to the bottom surface of the sealing resin;

a lead terminal portion including the inner connecting portion and the outer connecting portion has a wide portion and a narrow portion at sifted positions in the longitudinal direction thereof in plan view; and

a part of the sealing resin enters an underside of the inner connecting portion to form the inner connecting portion sealing resin.

Claim 15 (Newly Presented): A semiconductor device as claimed in claim 14, in which at least a part of the lead terminal portion has a cross-section, that is taken along a plane that is perpendicular to the longitudinal direction of the lead terminal portion, in a shape of an inverted trapezoid.

Claim 16 (Newly Presented): A semiconductor device as claimed in claim 14, in which a step is formed between a lower surface of the outer connecting portion and the lower surface of the inner connecting portion.

Claim 17 (Newly Presented): A semiconductor device as claimed in claim 14, in which a tapered surface, which comes upwardly as it comes inwardly of the sealing resin, is provided between a lower surface of the outer connecting portion and the lower surface of the inner connecting portion.

Claim 18 (Newly Presented): A semiconductor device as claimed in claim 14, in which a bottom surface of the outer connecting portion is exposed from the bottom surface of the sealing resin to form an outer lead portion.

Claim 19 (Newly Presented): A semiconductor device comprising:  
a lead frame having inner connecting portions and outer connecting portions;  
a semiconductor chip having electrodes on a surface thereof;

metal wires for electrically connecting the electrodes on the semiconductor chip and the inner connecting portions of the lead frame;

a sealing resin for sealing the inner connecting portions of the lead frame, the semiconductor chip and the metal wires therein, and at the same time exposing the outer connecting portions of the lead frame at a bottom surface thereof; and

an inner connecting portion sealing resin for covering the inner connecting portion at the bottom side of the sealing resin; wherein

the inner connecting portion sealing resin exists beneath the connecting portion of the inner connecting portion with the metal wires;

each of the metal wires is bonded to an upper surface of the inner connecting portion;

a lower surface of the inner connecting portion is offset inwardly of the sealing resin with respect to the bottom surface of the sealing resin;

at least a part of a lead terminal portion including the inner connecting portion and the outer connecting portion has a cross-section, that is taken along a plane that is perpendicular to the longitudinal direction of the lead terminal portion, in a shape of an inverted trapezoid; and

a part of the sealing resin enters an underside of the inner connecting portion to form the inner connecting portion sealing resin.

Claim 20 (Newly Presented): A semiconductor device as claimed in claim 19, in which a tapered surface, which comes upwardly as it comes inwardly of the sealing

resin, is provided between a lower surface of the outer connecting portion and the lower surface of the inner connecting portion.

Claim 21 (Newly Presented): A semiconductor device as claimed in claim 19, in which a bottom surface of the outer connecting portion is exposed from the bottom surface of the sealing resin to form an outer lead portion.

Claim 22 (Newly Presented): A lead frame comprising:

a supporting portion for supporting a semiconductor chip; and

lead terminal portions each having an inner connecting portion to be electrically connected to the semiconductor chip to be mounted on the supporting portion and an outer connecting portion for outer connection;

a lower surface of the inner connecting portion being offset with respect to a lower surface of the outer connecting portion so that an inner connecting portion sealing space is defined below the inner connecting portion; wherein

an area for electrically connecting the semiconductor chip is provided above the inner connecting portion sealing space;

the lead terminal portion has a wide portion and a narrow portion at sifted positions in the longitudinal direction thereof in plan view.

Claim 23 (Newly Presented): A lead frame as claimed in claim 22, in which at least a part of the lead terminal portion has a cross-section, that is taken along a plane

that is perpendicular to the longitudinal direction of the lead terminal portion, in a shape of an inverted trapezoid.

Claim 24 (Newly Presented): A lead frame as claimed in claim 22, in which a step is formed between the lower surface of the outer connecting portion and the lower surface of the inner connecting portion.

Claim 25 (Newly Presented): A lead frame as claimed in claim 22, in which a tapered surface, which comes upwardly as it comes toward the supporting portion, is provided on the lower surface of the inner connecting portion.

Claim 26 (Newly Presented): A lead frame comprising:

- a supporting portion for supporting a semiconductor chip; and
- lead terminal portions each having an inner connecting portion to be electrically connected to the semiconductor chip to be mounted on the supporting portion and an outer connecting portion for outer connection;
- a lower surface of the inner connecting portion being offset with respect to a lower surface of the outer connecting portion so that an inner connecting portion sealing space is defined below the inner connecting portion; wherein
- an area for electrically connecting the semiconductor chip is provided above the inner connecting portion sealing space,

at least a part of the lead terminal portion has a cross-section, that is taken along a plane that is perpendicular to the longitudinal direction of the lead terminal portion, in a shape of an inverted trapezoid.

Claim 27 (Newly Presented): A lead frame as claimed in claim 35, in which a tapered surface, which comes upwardly as it comes toward the supporting portion, is provided on the lower surface of the inner connecting portion.